SLOS074 - D2785, OCTOBER 1983 — REVISED JUNE 1988

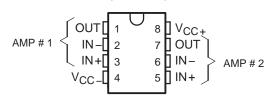
- Matched Gain and Offset Between Amplifiers
- Unity-Gain Bandwidth . . . 3 MHz Min
- Slew Rate . . . 1.5 V/ns Min
- Low Equivalent Input Noise Voltage
 2 μV/Hz Max (20 Hz to 20 kHz)
- No Frequency Compensation Required
- No Latch Up
- Wide Common-Mode Voltage Range
- Low Power Consumption
- Designed to be Interchangeable with Raytheon RC4559

AVAILABLE OPTIONS

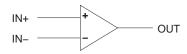
SYMBO	LIZATION	OPERATING			
DEVICE	PACKAGE SUFFIX	TEMPERATURE RANGE	V _{IO} max at 25°C		
RC4559	D, P	−0°C to 70°C	6 mV		

The D packages are available taped and reeled. Add the suffix R to the device type when ordering. (i.e., RC4559DR)

D OR P PACKAGE (TOP VIEW)



symbol (each amplifier)



description

The RC4559 is a dual high-performance operational amplifier. The high common-mode input voltage and the absence of latch-up make this amplifier ideal for low-noise signal applications such as audio preamplifiers and signal conditioners. This amplifier features a guaranteed dynamic performance and output drive capability that far exceeds that of the general-purpose type amplifiers.

The RC4559 is characterized for operation from 0°C to 70°C.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage V _{CC+} (see Note 1)	18 V
Supply voltage V _{CC} (see Note 1)	-18 V
Differential input voltage (see Note 2)	±30 V
Input voltage (any input, see Notes 1 and 3)	±15 V
Duration of output short-circuit to ground, one amplifier at a time (see Note 4) unl	imited
Continuous total dissipation 50	0 mW
Operating free-air temperature range 0°C to	70°C
Storage temperature range –65°C to	125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- NOTES: 1. All voltage values, unless otherwise noted, are with respect to the zero reference level (ground) of the supply voltages where the zero reference level is the midpoint between V_{CC+} and V_{CC-} .
 - 2. Differential voltages are at the noninverting input terminal with respect to the inverting input terminal.
 - 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 volts, whichever is less.
 - 4. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.



RC4559 DUAL HIGH-PERFORMANCE OPERATIONAL AMPLIFIER

electrical characteristics at specified free-air temperature, $V_{CC+} = 15 \text{ V}$, $V_{CC-} = -15 \text{ V}$

	PARAMETER	TEST CONDITIONS†	T _A ‡	MIN	TYP	MAX	UNIT
\ /	land effect wells as		25°C		2	6	mV
VIO	Input offset voltage	VO = 0	Full Range			7.5	IIIV
lio	land offert comment	V- 0	25°C		5	100	A
lio	Input offset current	VO = 0	Full range			200	nA
lini	nput bias current	Va - 0	25°C		40	250	nA
I _{IB} I	riput bias current	VO = 0	Full range			500	ПА
٧ _I	Input voltage range		25°C	±12	±13		V
		$R_L \ge 3 \text{ k}\Omega$	25°C	±12	±13		
VOM	Maximum peak output voltlage swing	$R_L = 600 \Omega$	25°C	±9.5	±10		V
		$R_L \ge 2 k\Omega$	Full range	±10			
		$V_0 = \pm 10 \text{ V},$	25°C	20	300		
VI	Input voltage range	$R_L = 2 k\Omega$	Full range	15			V/mV
BOM	Maximum output-swing bandwidth	V _{OPP} = 20 V, R _L = 2 kΩ	25°C	24	32		kHz
B ₁	Unity-gain bandwidth		25°C	3	4		MHz
rį	Input resistance		25°C	0.3	1		MΩ
CMRR	Common-mode rejection ratio	VO = 0	25°C	80	100		dB
ksvs	Supply voltage sensitivity (ΔV _{IO} /ΔV _{CC})	V _O = 0	25°C		10	75	μV/V
V _n	Equivalent input noise voltage (closed loop)	$A_{VD} = 100,$ $R_{S} = 1 \text{ k}\Omega,$ f = 20 Hz to 20 kHz	25°C		1.4	2	μV
In	Equivalent input noise current	f = 20 Hz to 20 kHz	25°C		25		pА
			25°C		3.3	5.6	
ICC	Supply current (both amplifiers)	No load, No signal	0°C		4	6.6	mA
			70°C		3	5	
V ₀₁ /V ₀₂	Crosstalk attentuation	$A_{VD} = 100,$ $R_{S} = 1 \text{ k}\Omega,$ f = 10 kHz	25°C		90		dB

[†] All characteristics are specified under open-loop operation, unless otherwise noted.

matching characteristics at $V_{CC+} = 15 \text{ V}$, $V_{CC-} = -15 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
VIO	Input offset voltage	V _O = 0	±0.2		mV
liO	Input offset current	VO = 0	±7.5		nA
I _{IB}	Input bias current	V _O = 0	±15		nA
AVD	Large-signal differential voltage amplification	$V_0 = \pm 10 \text{ V}, R_L = 2 \text{ k}\Omega$	±1		dB

operating characteristics, V_{CC+} = 15 V, V_{CC-} = -15 V, T_A = 25°C

	PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT	
t _r	Rise time	$V_{I} = 20 \text{ mV},$	$R_L = 2 k\Omega$,	$C_L = 100 pF$		80		μs
	Overshoot]				18%		
SR	Slew rate at unity gain	$V_{I} = 10 \text{ mV},$	$R_L = 2 k\Omega$,	$C_L = 100 pF$	1.5	2		V/μs



[‡] Full range operating free-air temperature range is 0°C to 70°C.





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
RC4559D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	RC4559	Samples
RC4559DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	RC4559	Samples
RC4559P	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	RC4559P	Samples
RC4559PE4	ACTIVE	PDIP	Р	8	50	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	0 to 70	RC4559P	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

6-Feb-2020

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

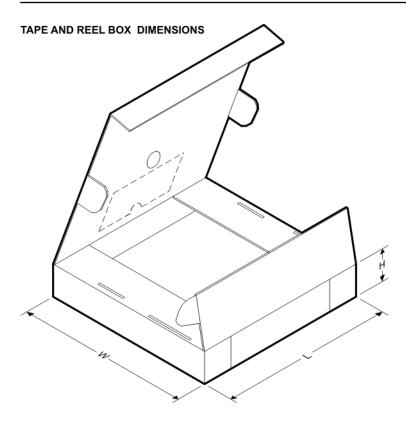
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

	Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
I	RC4559DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
RC4559DR	SOIC	D	8	2500	340.5	338.1	20.6

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.





SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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